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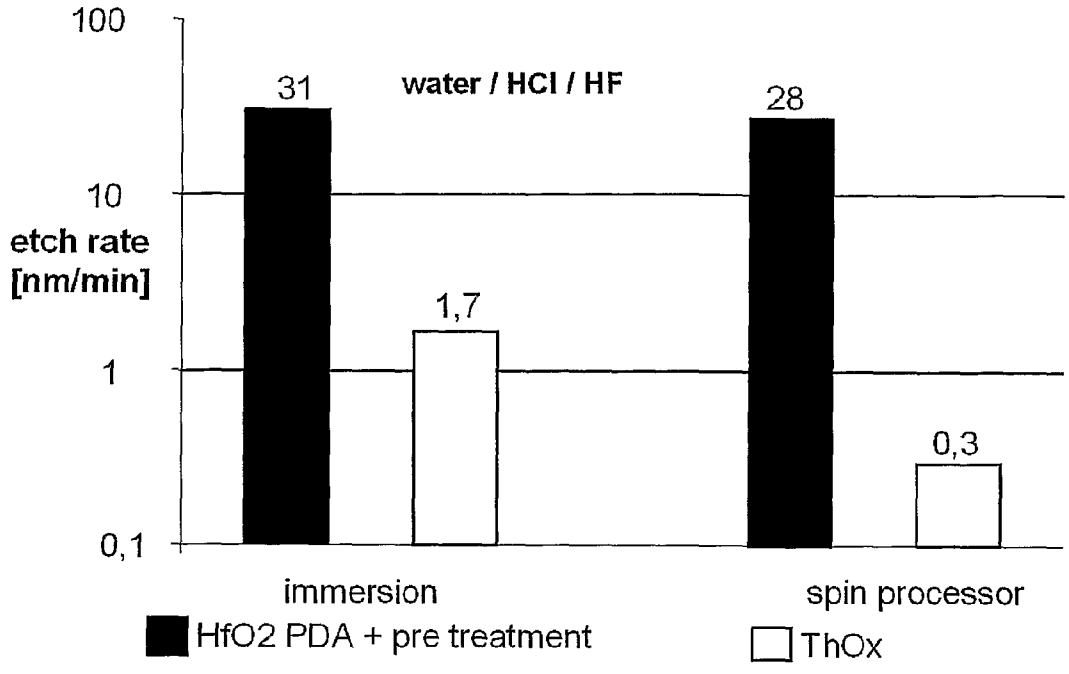
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(54) Title: METHOD FOR SELECTIVE ETCHING



(57) Abstract: Disclosed is a method of selective etching a first material on a substrate with a high selectivity towards a second material by flowing a liquid etchant across a substrate surface at a flow sufficient fast to generate a mininun mean velocity v parallel to the substrate's surface.

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